

信頼性試験成績書

1.2um Process Technology Product and Package Legacy Fujitsu Reliability Engineering Test Report

Wafer Process : Aizu Fujitsu
Assembly : J-Devices

Reliability Test 1

Device Type : MCU 1
Package Type : Plastic SSOP-20 Package

Test Item	Test Condition	Tested Number		Tested Time	Failed Number
High Temperature Operation Life 高温連続動作試験	150 °C V _{DD} =Maximum Rating	55		1000h	0
Temperature Humidity Bias 高温連続動作試験	85 °C / 85% RH V _{DD} =Maximum Rating	25	(a)	1000h	0
High Temperature Storage 高温保存試験	150 °C	25		1000h	0
Temperature Cycling 温度サイクル	-65°C~150°C	55	(a)	200cyc	0
Thermal Shock 熱衝撃	0°C~100°C	25		200cyc	0
Pressure Cooker Test	121°C, 100%RH: 2.03E5 Pa	55	(a)	168h	0
Pressure Cooker Test with Bias	121°C, 100%RH: 2.03E5 Pa V _{DD} =Maximum Rating	25	(a)	96h	0

(a) Pre-condition: Baking (125°C, 24h) +Moisture Absorption (85°C/85%RH, 24h) +IR 245°C Max.

Reliability Test 2

Device Type : MCU 2
Package Type : Plastic SOP-16 Package

Test Item	Test Condition	Tested Number	Tested Time	Failed Number
High Temperature Storage 高温保存試験	150 °C	26	(b) 1000h	0
Temperature Cycling 温度サイクル	-65°C~150°C	46	(b) 500cyc	0
Pressure Cooker Test	121°C, 100%RH: 2.03E5 Pa	26	(b) 168h	0
Pressure Cooker Test with Bias	121°C, 100%RH: 2.03E5 Pa V _{DD} =Maximum Rating	26	(b) 96h	0

(b) Pre-condition: Baking (125°C, 24h) +Moisture Absorption (85°C/85%RH, 48h) +IR 245°C Max.



Document History Page

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Rev.	ECN No.	Orig. of Change	Description of Change
**	5769794	KUMI	Initial release.